

## SHIELD

## Security and Access

### Background

**SHIELD Dielet Provides Hardware Root of Trust and Full Authentication Functionality in a Microscopic Integrated Circuit with RF Link**

**Electronics Counterfeiting a Threat to Military Electronics Integrity**

"Over a two year period, from 2009 to 2010, approximately 1,800 cases of suspect counterfeit parts were uncovered"

*Inquiry Into Counterfeit Electronic Parts in the Department of Defense Supply Chain, May 2012*

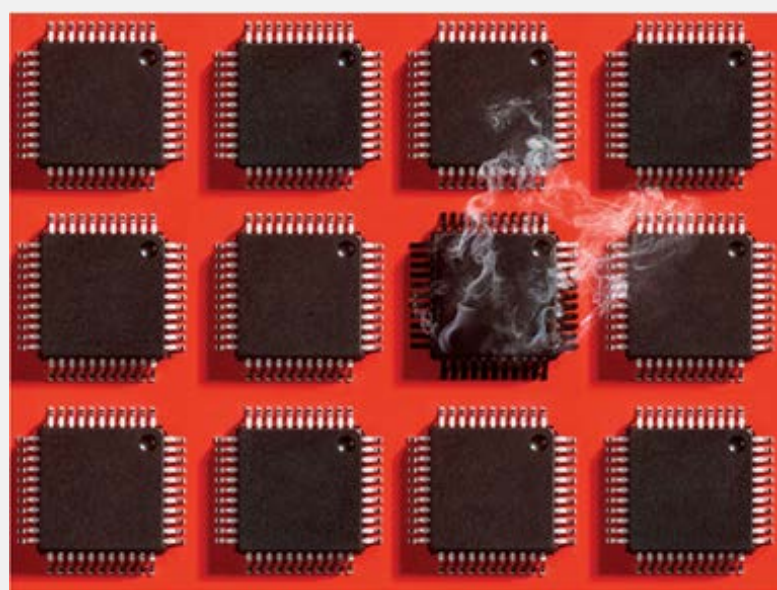


Image Source: IEEE Spectrum

**SHIELD Defeats Counterfeiting by Building a Complete Electronics Authentication System**

**Domain expertise assembled for SHIELD team**

Northrop Grumman Corporation, RFID Global Solution, Georgia Tech, Sandia National Labs, Kilopass, Corwill Technology

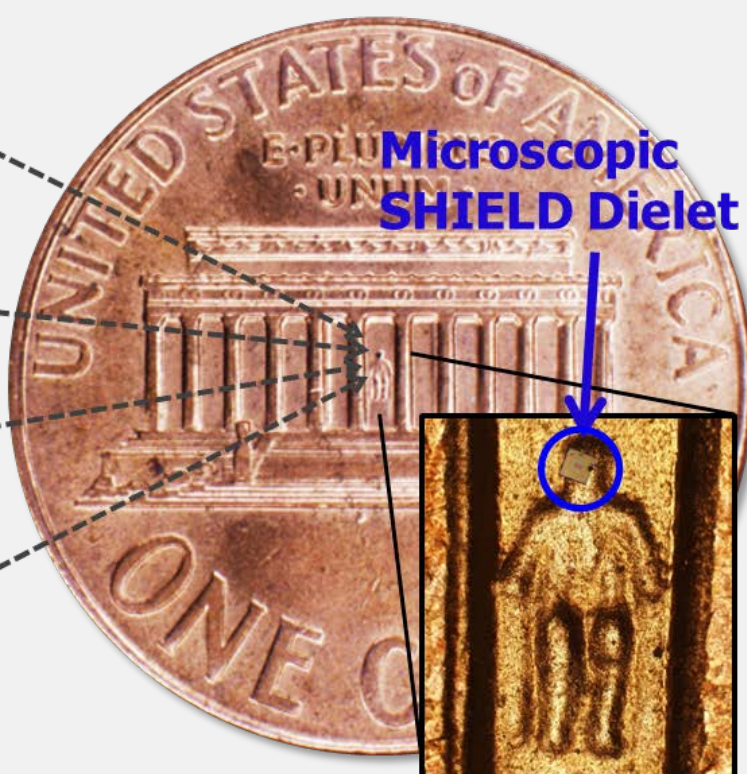
Global Asset Tracking Management Network



Image Source: CDW

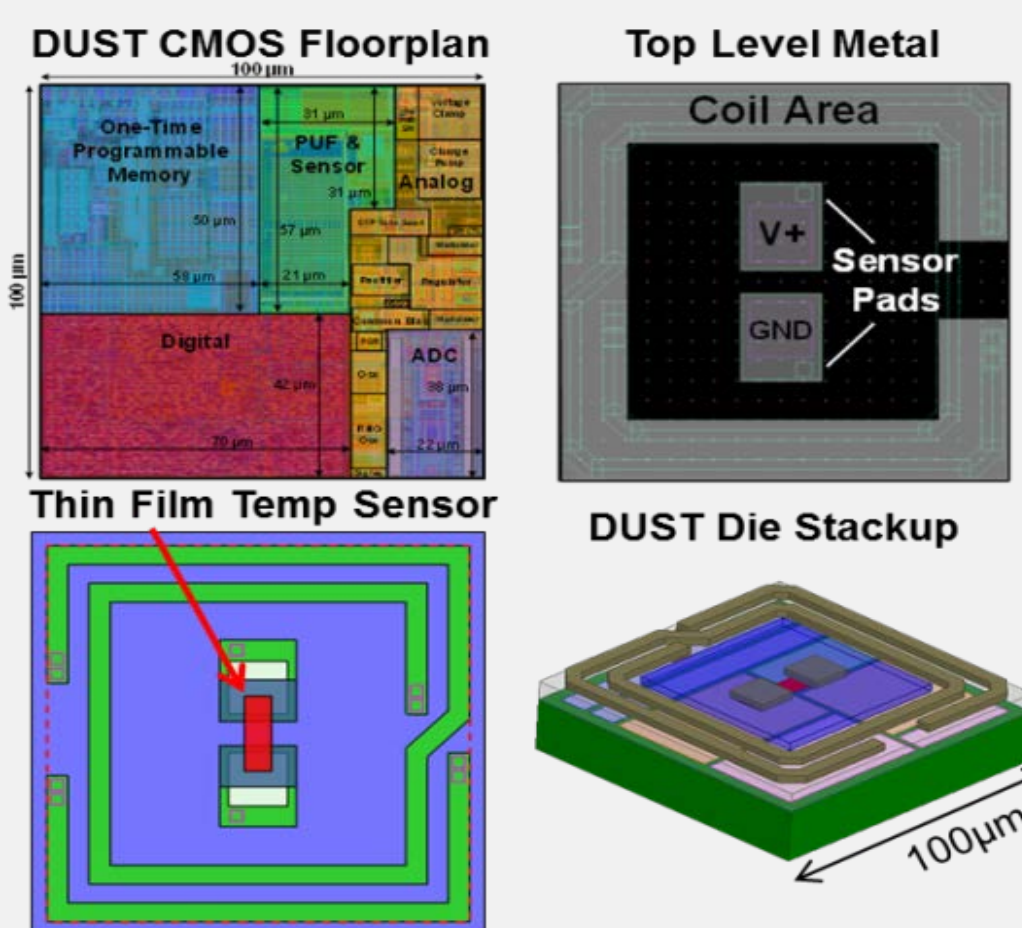


Dielet Inserted in Host Chip & Probed for Authentication  
Full Encryption Engine  
Unpowered Passive Sensors  
Inductive Powering and Communication

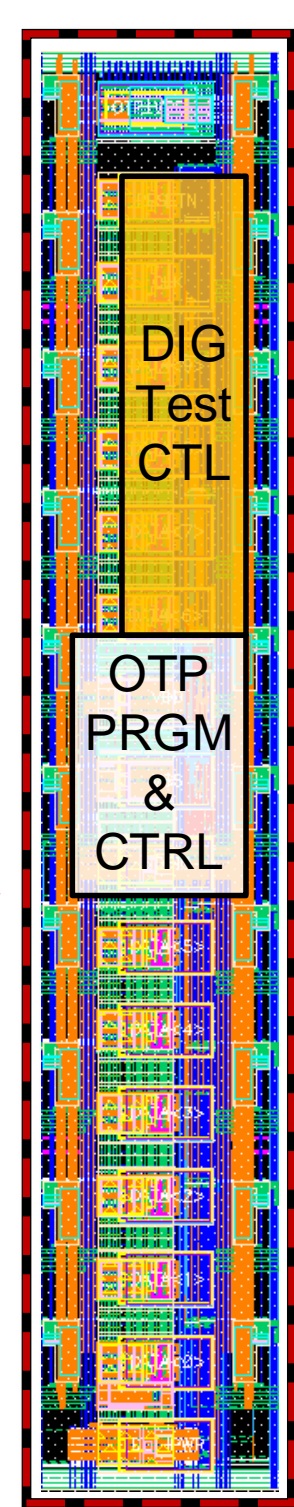
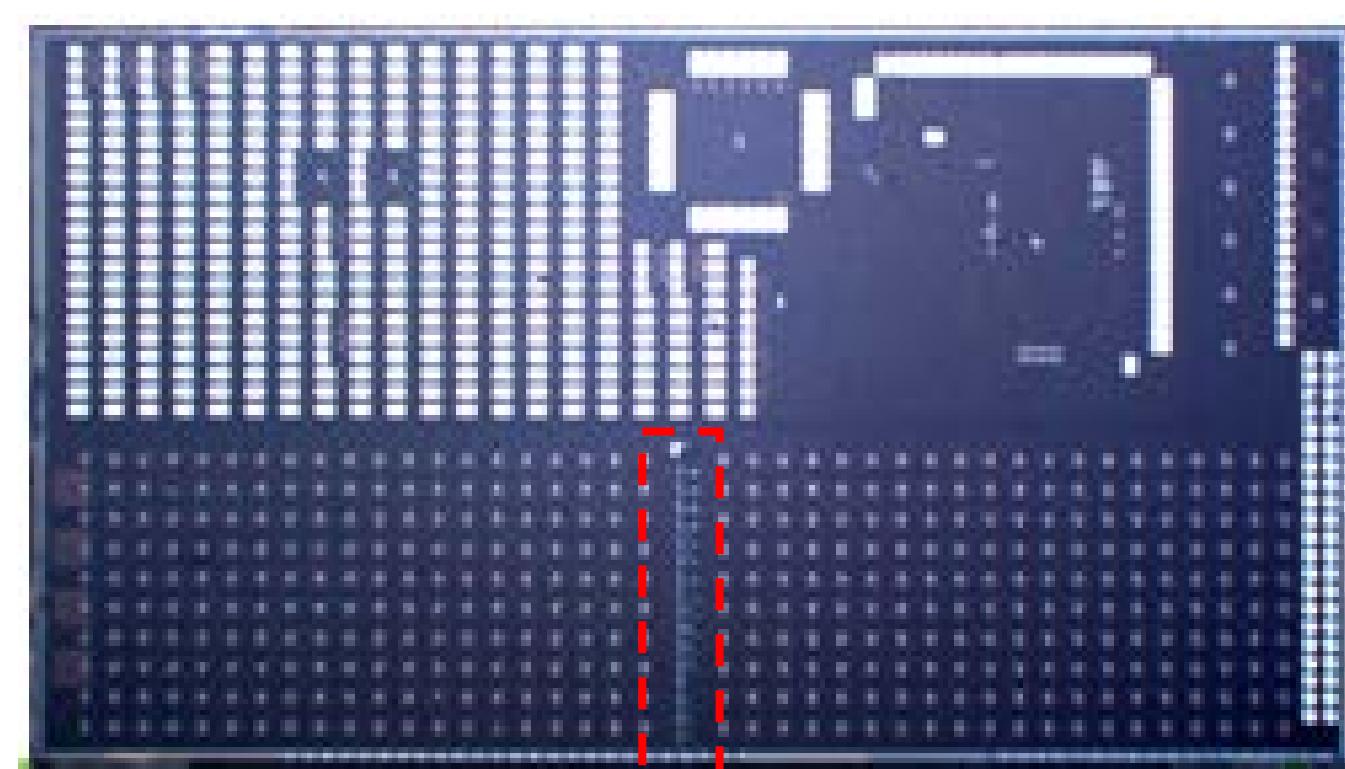


Microscopic Dielet Inserted into Every Electronics Package

**Each Dielet Supports a High Level of Functionality; Developed in 14nm CMOS**



**Wafer Scale Probing of Dielets uses Test Controller, Maximizing Dielet Density on Wafer, Minimizing Test Time and Cost**



**Dielet Array**

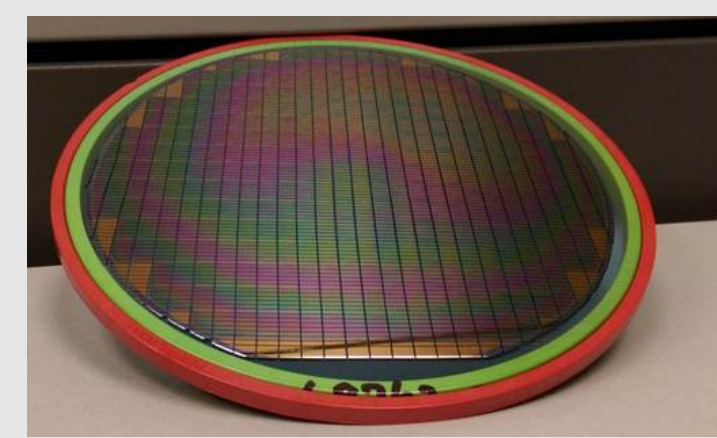
- Local decoding allows single dielet Power On/Communication
- Simultaneous ATPG scan of entire row (20 dielets) also possible

**Test Controller**

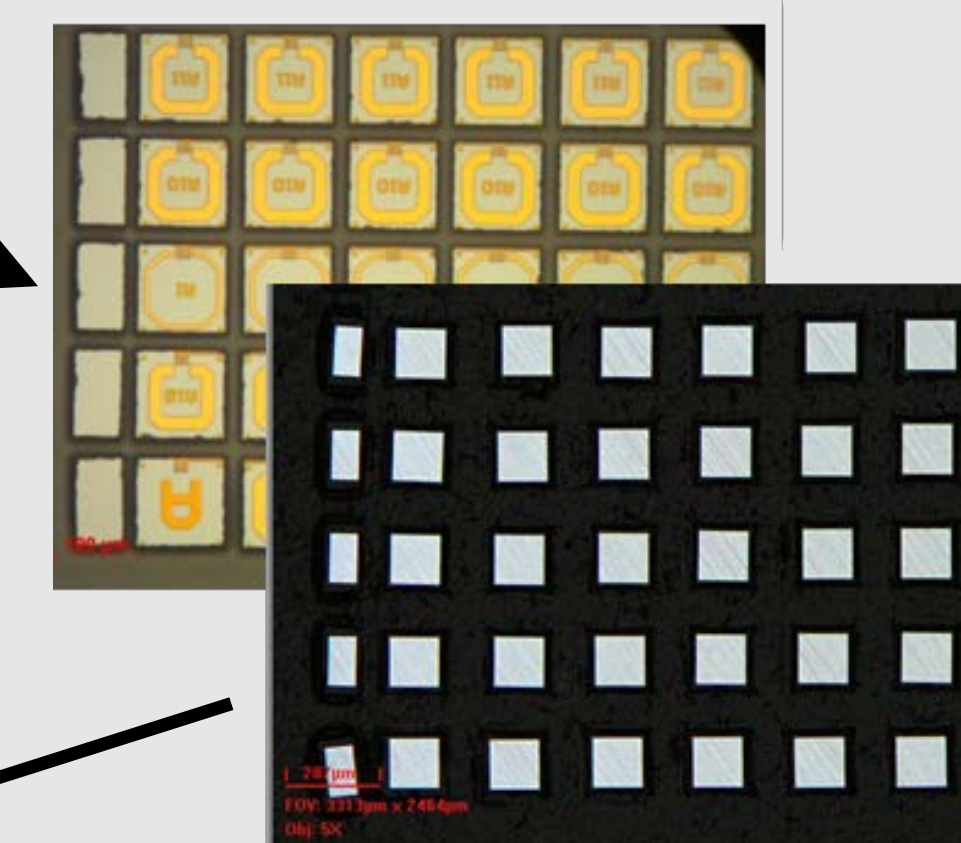
- Programs and reads back 400 OTP S/Ns with single touch-down
- Reads raw PUF bits to form a bit mask
- Integrates with Probe functionality to allow full authentication
- Provides visibility into each dielet's digital core

### Approach

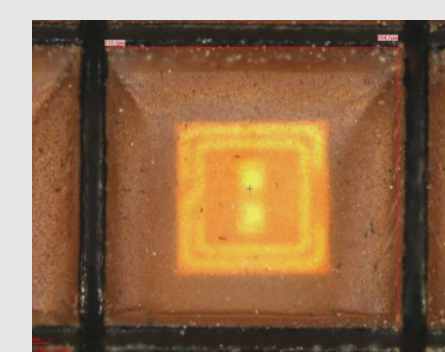
**Dielet Stretching and Encapsulation Protects Dielets and Allows Handling with Standard Tooling**



Surrogate wafer fabricated in house



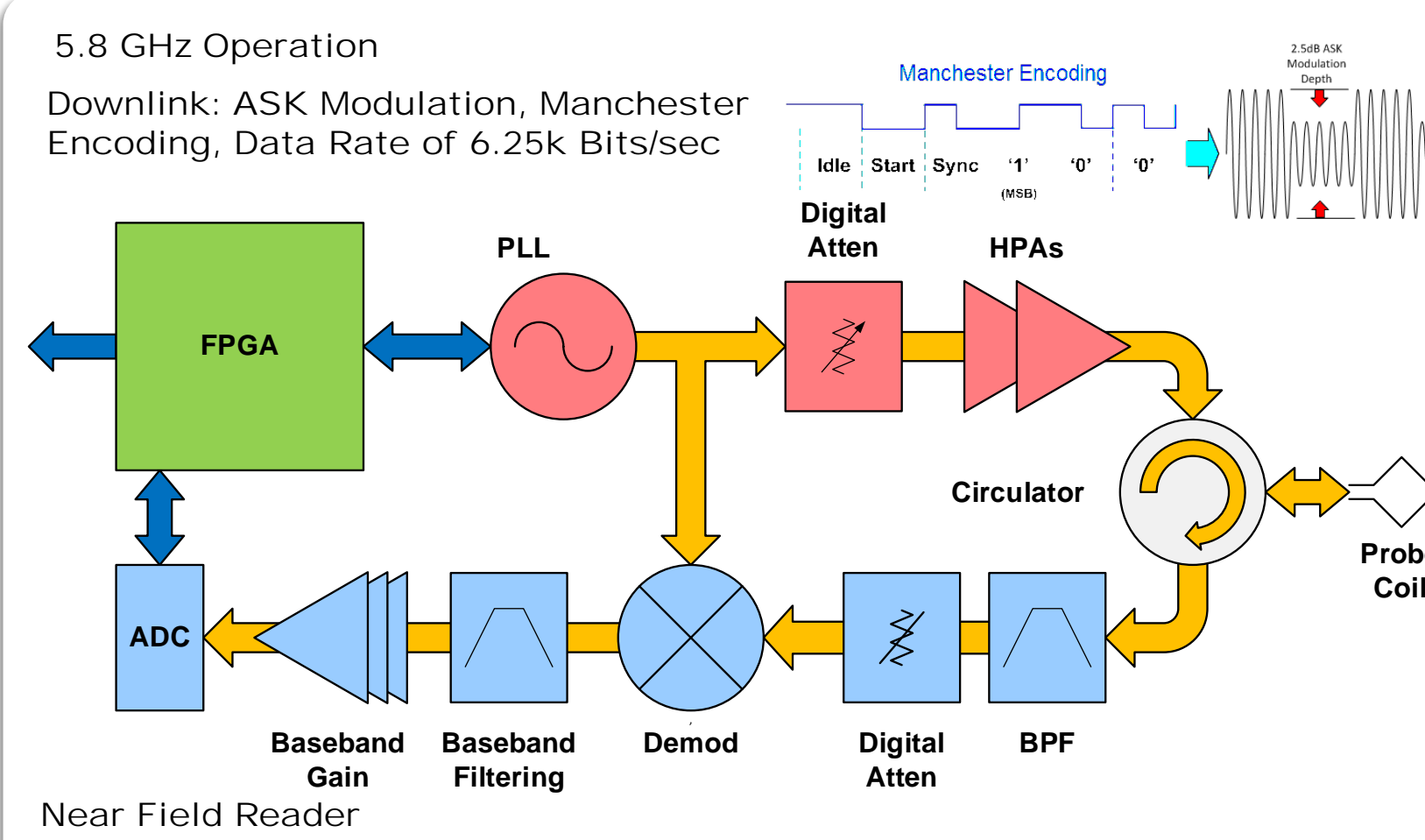
Die are singulated and spread on dice tape to increase effective die footprint



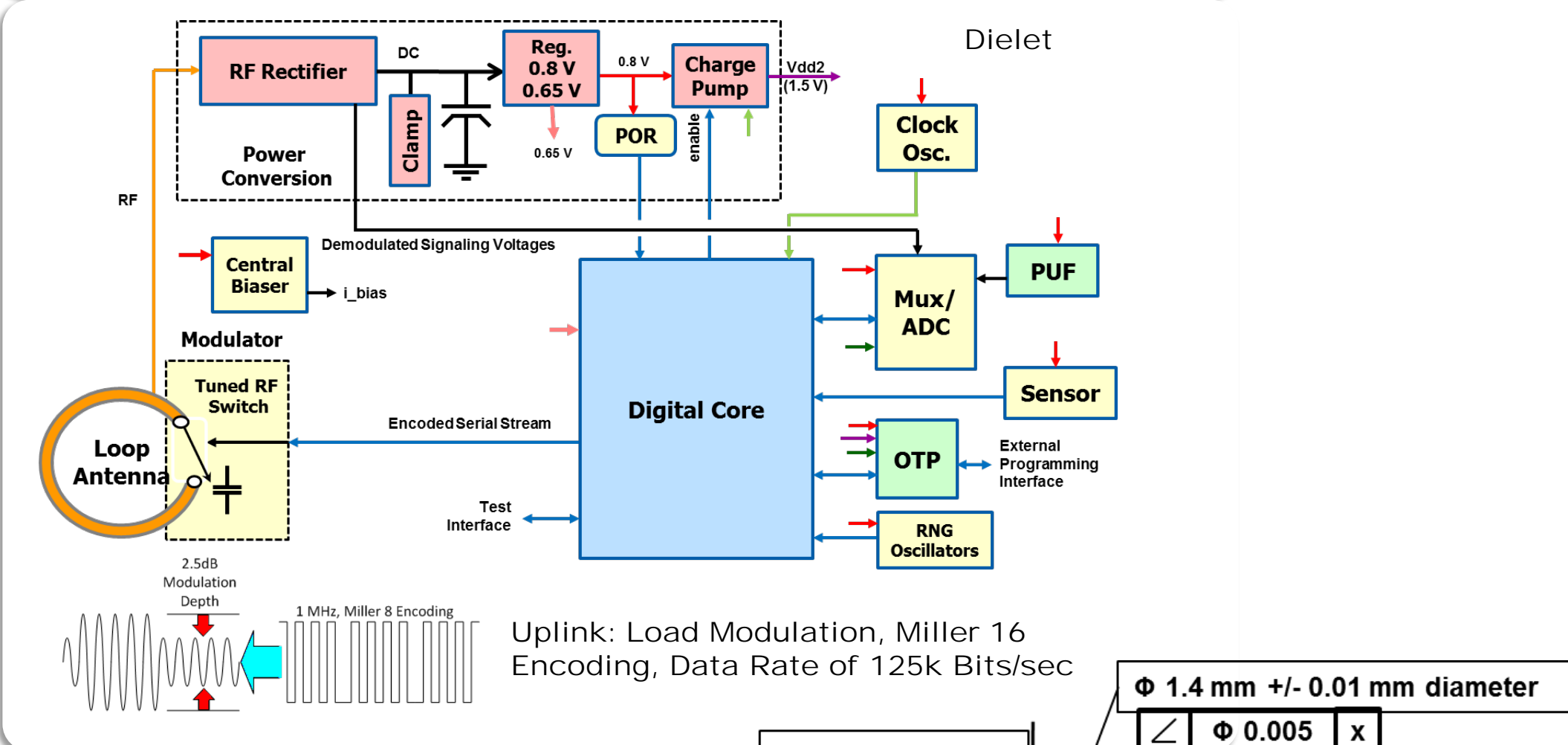
Fully encapsulated die provide enhanced mechanical robustness

Image Source: Georgia Tech Packaging Resource Center

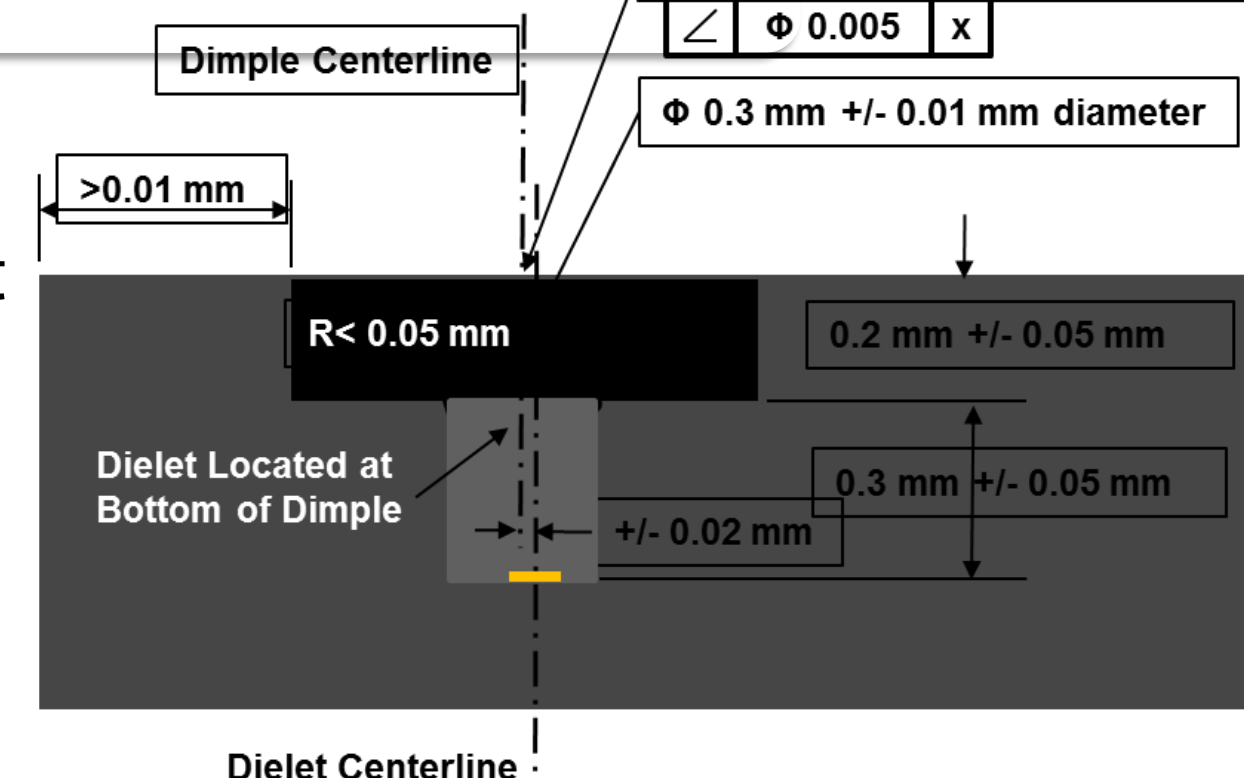
**Near Field Reader Architecture Uses Single Coil, Single Frequency System for Simultaneous Power Transfer and Bidirectional Communications**



Near Field Reader



**Mechanical Insertion of Dielet Into Microelectronics Package**



This research was developed with funding from the Defense Advanced Research Projects Agency (DARPA).

The views, opinions and/or findings expressed are those of the author and should not be interpreted as representing the official views or policies of the Department of Defense or the U.S. Government.

Distribution Statement - To Be Completed By DARPA.

### Results and Impact

**Temperature Sensor Detects Whether Part Has Experienced Reflow Temperatures**

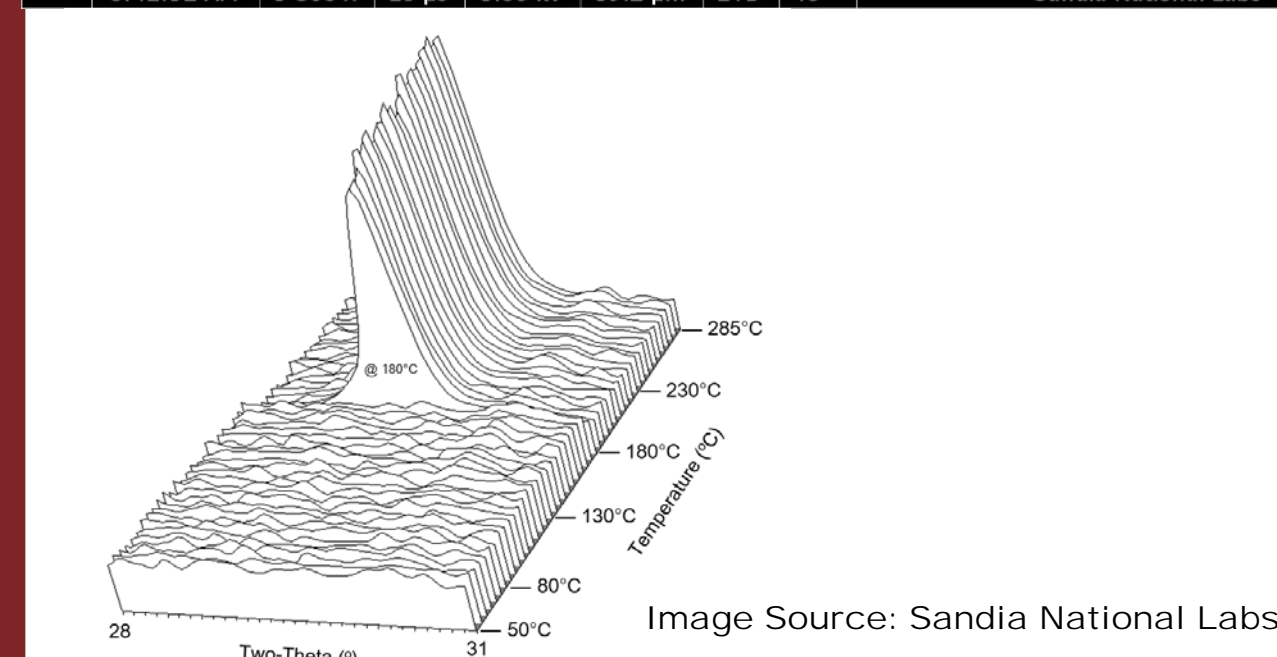
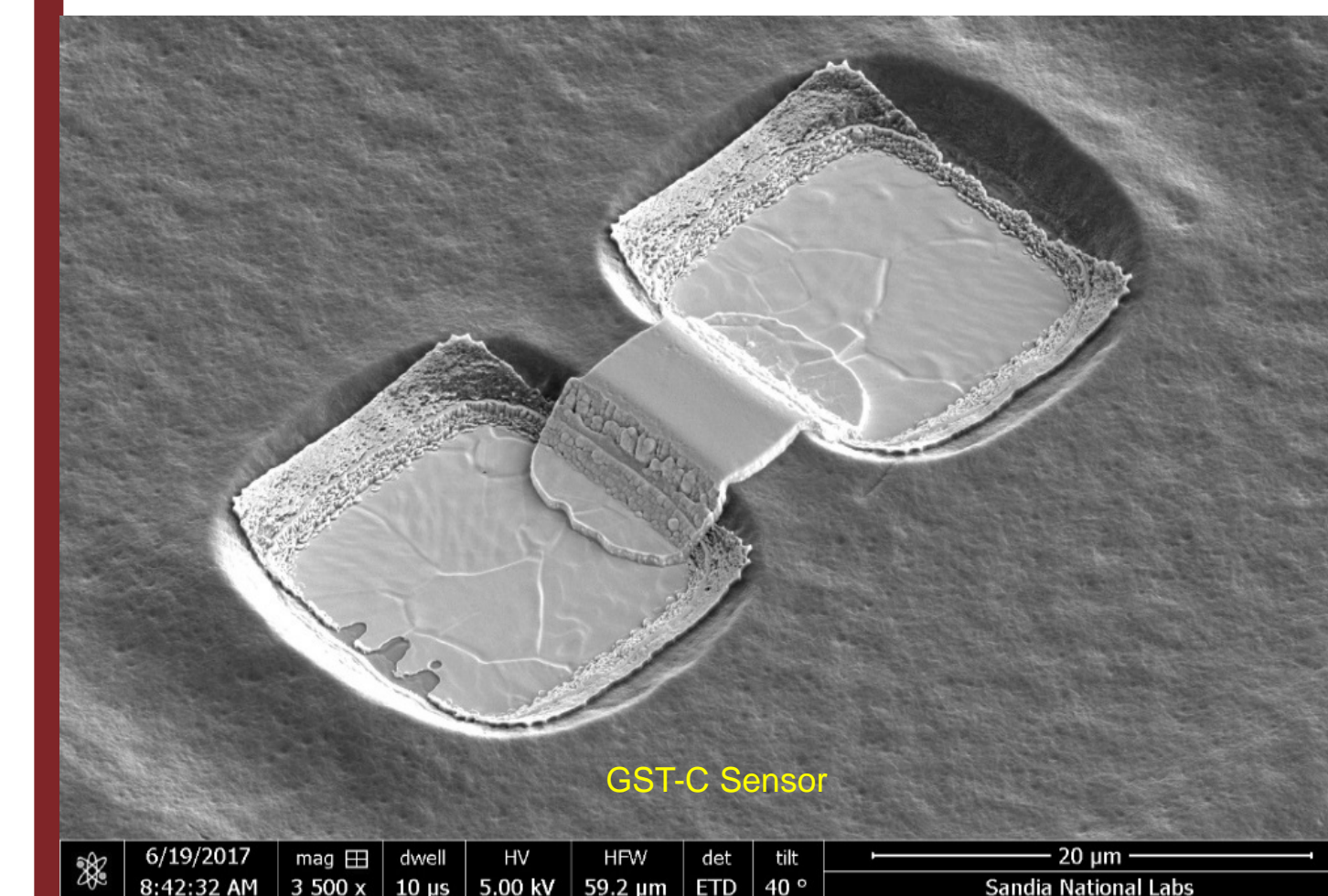
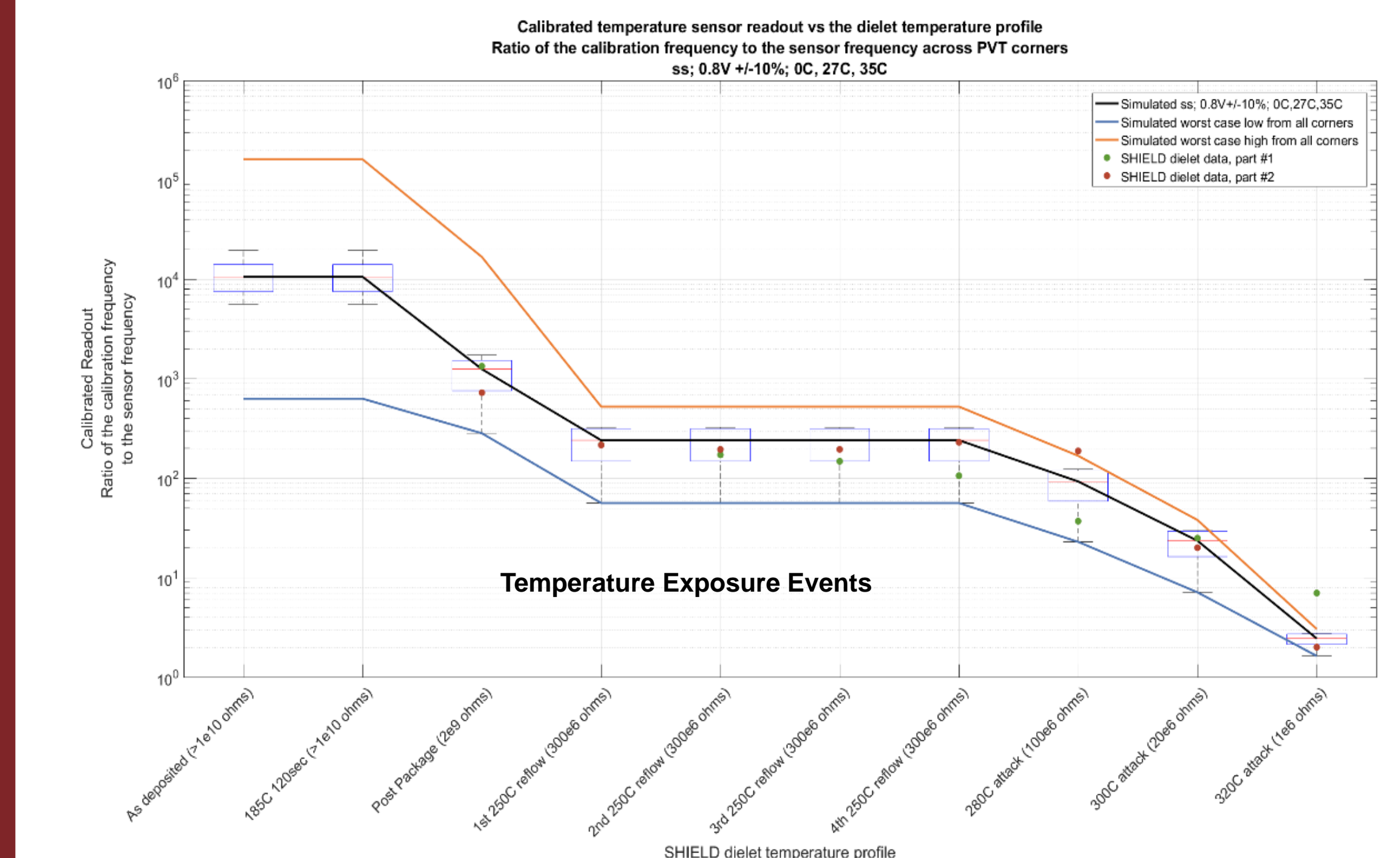
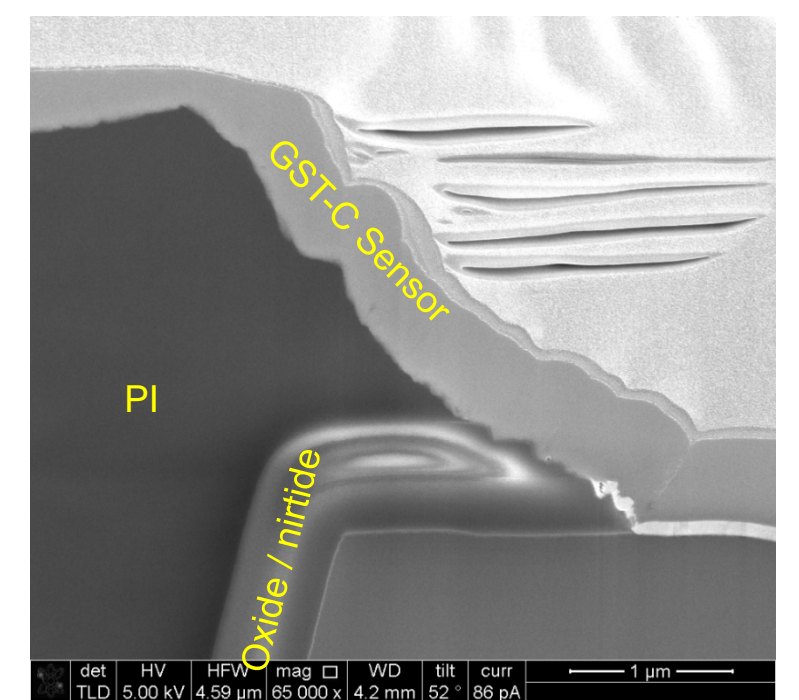
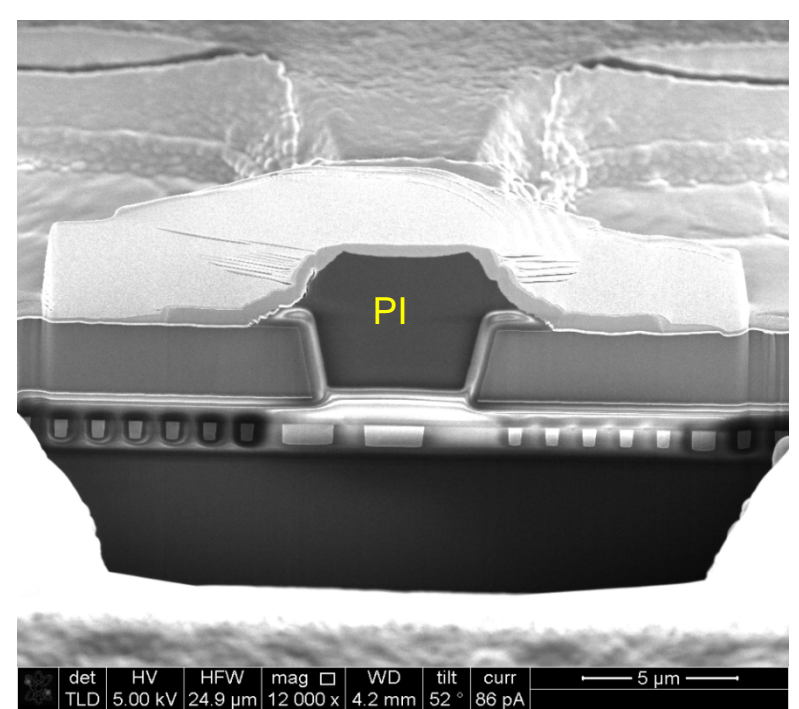


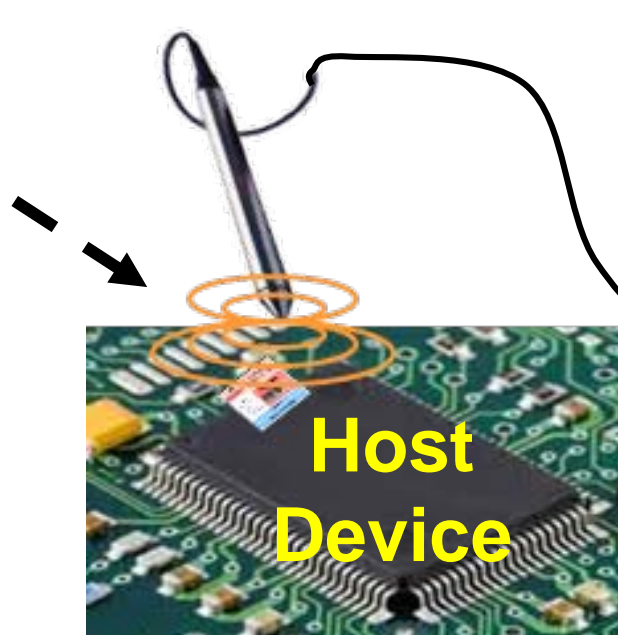
Image Source: Sandia National Labs



**Under the T&AM proposed program, managed by Army AvMC Protective Technologies, the SHIELD Range Extension and Enhanced Temperature Sensor will result in:**

- A microscopic dielet with a Near Field RF link with a > 3mm range implemented in Global Foundries 12 nm CMOS
- Challenge Response Protocol for Authentication and Dual key AES Encryption using Physically Unclonable Function and One-Time Programmable keys
- Enhanced Temperature History Sensor for Wider Range of Tamper Detection
- Reader using passive (reflectivity modulation) RFID technique

**SHIELD Dielet**



Authentication Database

**Impact: Provides an automated, dependable counterfeit avoidance method**